



CONSEJO SUPERIOR
DE INVESTIGACIONES
CIENTÍFICAS



The PreProcessor modules for the ATLAS Tile Calorimeter at the HL-LHC



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On behalf of the TileCal Upgrade group

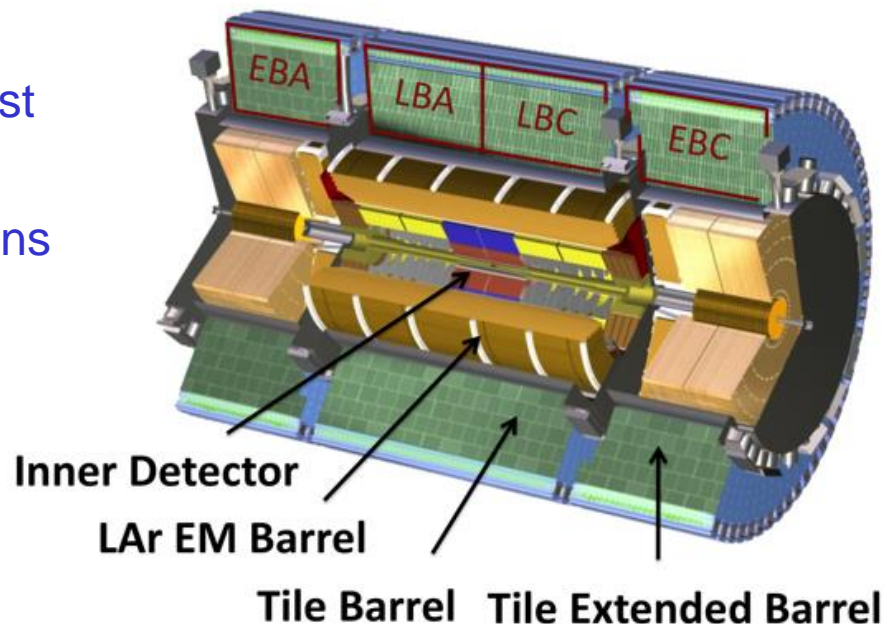
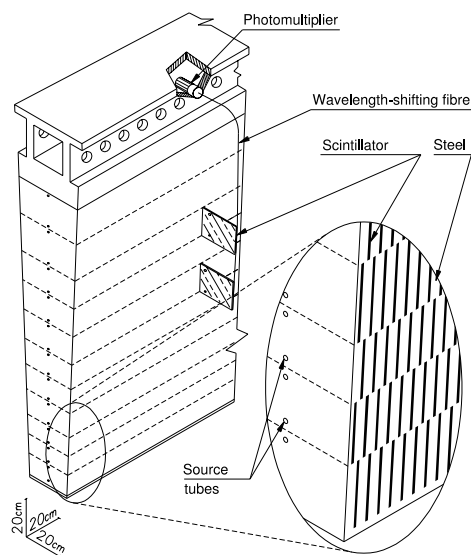


- Tile Calorimeter and Phase II Upgrade
- Development of new readout electronics
- Status of the full-size PreProcessor modules
- Summary

ATLAS Tile Calorimeter



- Segmented calorimeter of steel plates and plastic scintillator tiles which covers the most central region of the ATLAS experiment
- Measures energies of hadrons, jets, τ -leptons and E_T^{miss}
- 4 partitions: EBA, LBA, LBC, EBC
- Each partition has 64 modules
 - One drawer hosts up to 48 PMTs

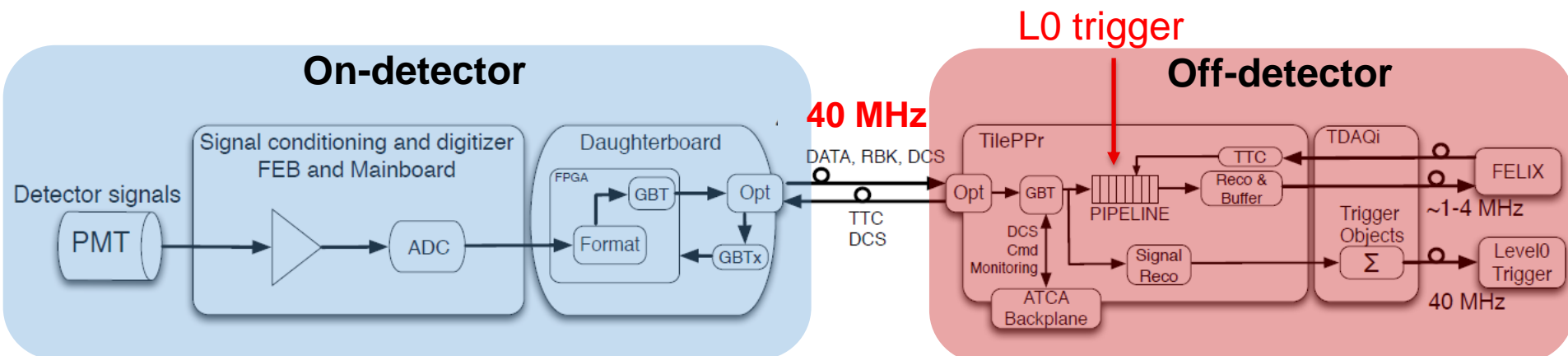


- Light produced by a charged particle passing through a plastic scintillating tile is transmitted to the PMTs
- Scintillator tiles are read out using wavelength shifting fibers coupled to PhotoMultiplier Tubes (PMTs)
- Around 10,000 readout channels

TileCal Phase II Upgrade

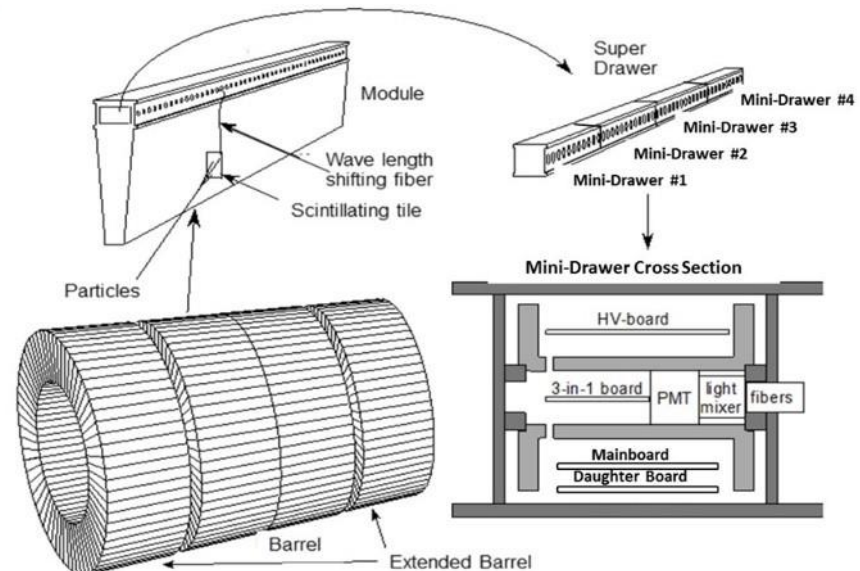
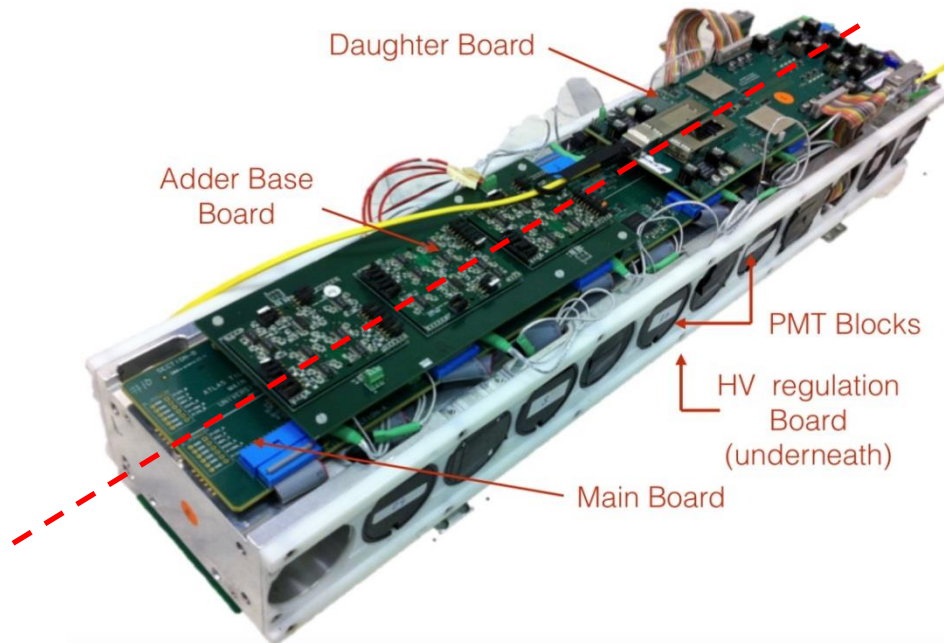


- Large Hadron Collider plans to increase the instantaneous luminosity by a factor 5-7 around 2027 → High Luminosity-LHC
- Complete replacement of on-detector and off-detector readout electronics
 - Aging of electronics due to time and radiation
 - Current readout system is not compatible with Phase II TDAQ architecture
- New readout strategy for HL-LHC
 - On-detector electronics will transmit digitized data to the off-electronics at the LHC frequency (40 MHz) → **40 Tbps to read out the entire detector!**
 - Buffer pipelines are moved to off-detector electronics
 - Redundancy in data links and power distribution → improve system reliability





- The **Phase II module** is composed of 4 mini-drawers (48 PMTs). Each mini-drawer have 2 independent read out sections **for redundant cell readout**
 - 12 PMTs + 12 front-end boards reading out 6 TileCal cells
 - 1 × MainBoard: operation of the front-end boards
 - 1 × DaughterBoard: data high speed link with the off-detector electronics
 - 1 × High Voltage regulation board: Remote or Internal options
 - 1 × Low Voltage Power Supply (LVPS): low voltage power distribution





- **Core element of the off-detector electronics**

- Data processing and handling from detector
- Clock distribution towards the modules
- Detector Control System data distribution
- Interfaces with the ATLAS trigger and ATLAS readout systems (FELIX)

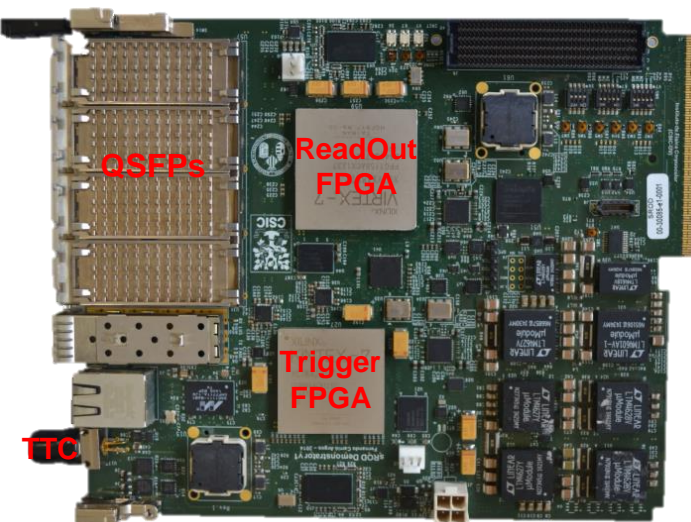
- **Fully functional prototype - Demonstrator**

- Xilinx Virtex 7 (48 GTX), Kintex 7 (28 GTX)
- 4 QSFPs, TX+RX Avago MiniPODs
- Double mid-size AMC (μ TCA / ATCA carrier)
- 1/8th of the full-size PreProcessor

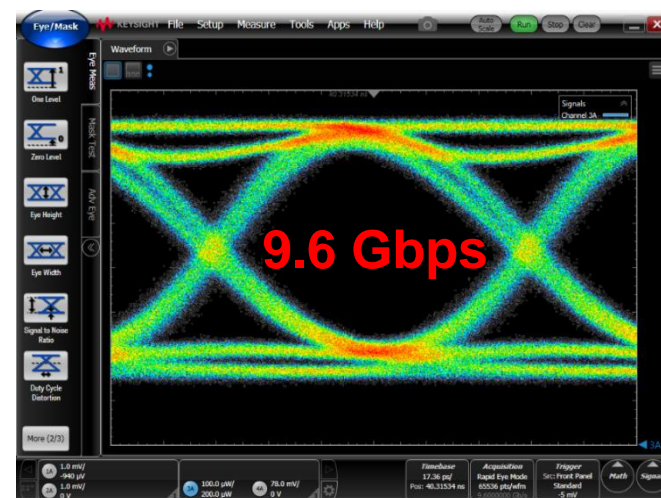
- **Operates 4 mini-drawers \rightarrow 160 Gbps!**

- **Bit Error Rate Tests**

- 16 links at 9.6 Gbps with PRBS31 pattern during 115 hours
- BER better than $5 \cdot 10^{-17}$ for a CL of 95%



PPr Demonstrator

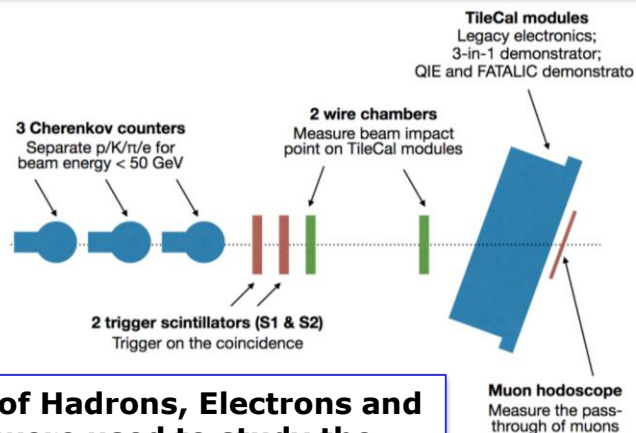


Eye diagram at 9.6 Gbps

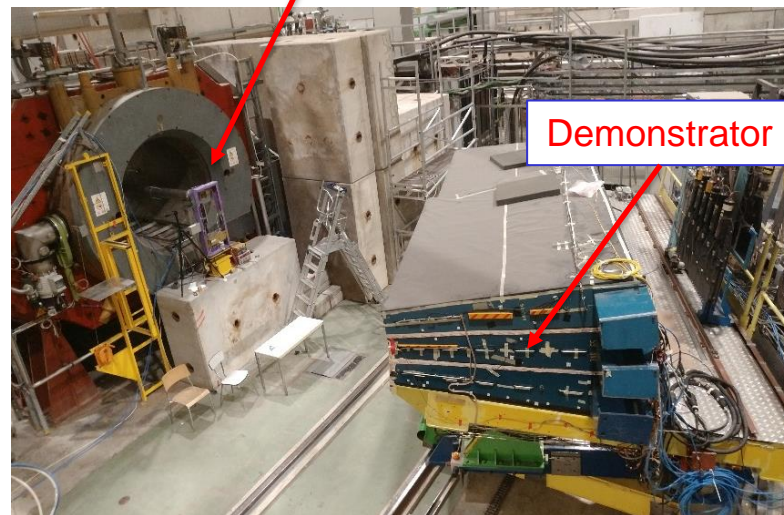
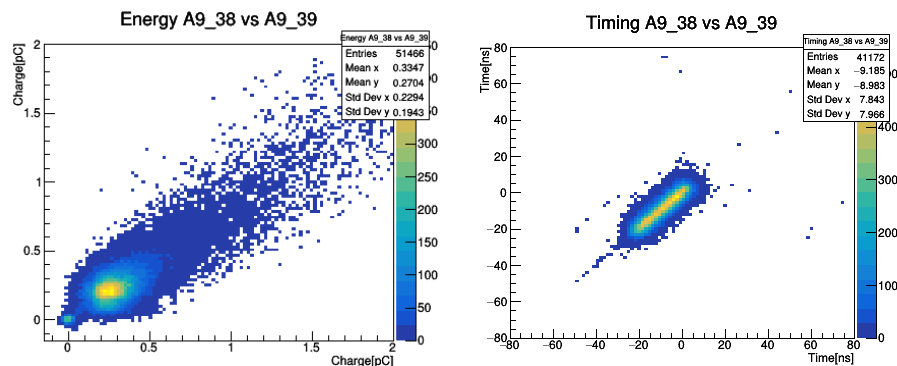
Test Beam setup



- Located at the **Super Proton Synchrotron (SPS)** North Area on the H8 beam line
- Detector modules equipped with upgraded and legacy electronics for performance comparison
- Fully integrated with the ATLAS TDAQ software and DCS system
 - Front-end electronics configuration
 - Physics, calibration and laser runs
 - HV and LV control/monitoring
- Data taking through FELIX / legacy system
- Phase II clock and readout architecture



Beams of Hadrons, Electrons and Muons were used to study the calorimeter response

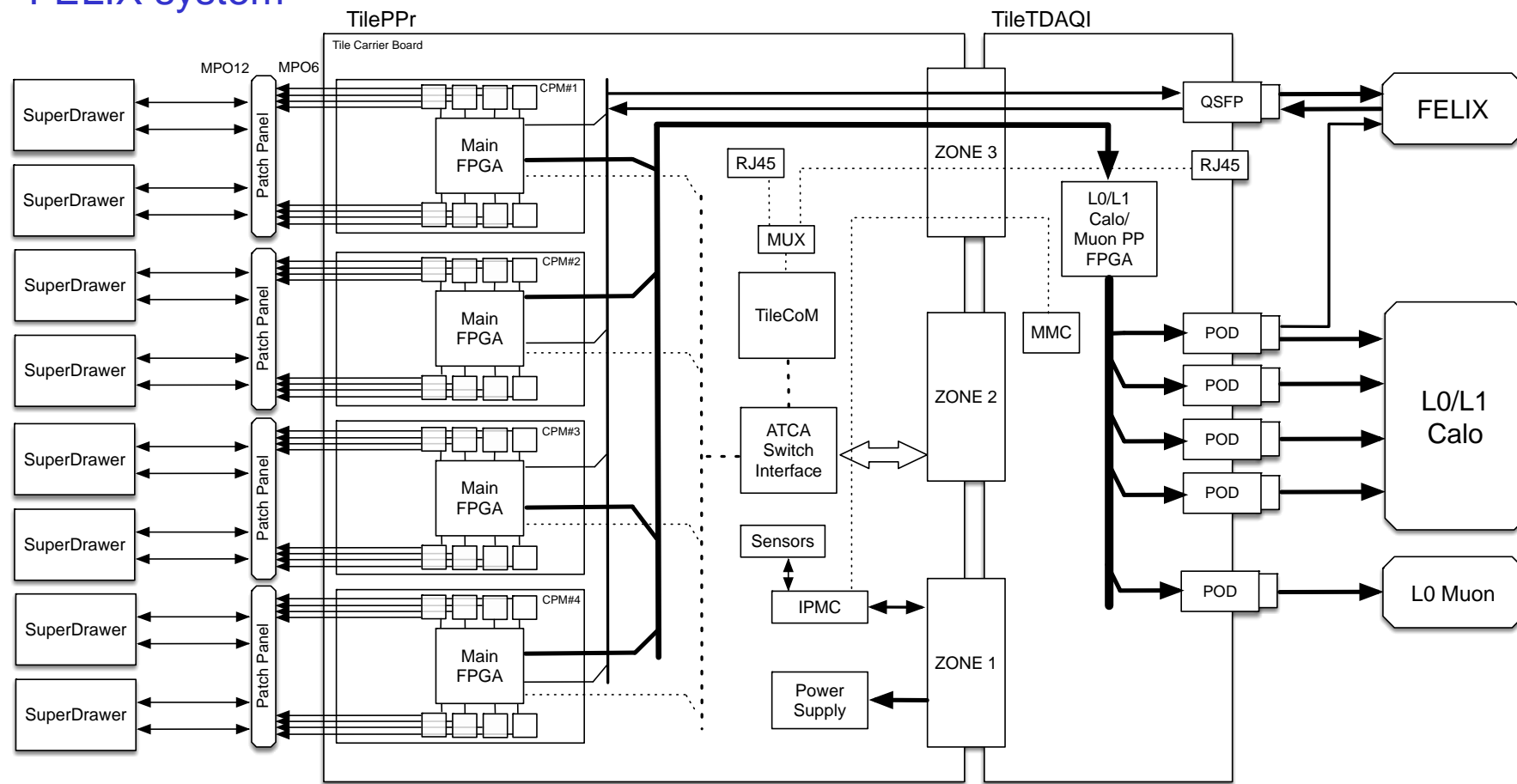


Test beam setup at H8 line

- **Insertion of a demonstrator module into the ATLAS experiment this Spring**



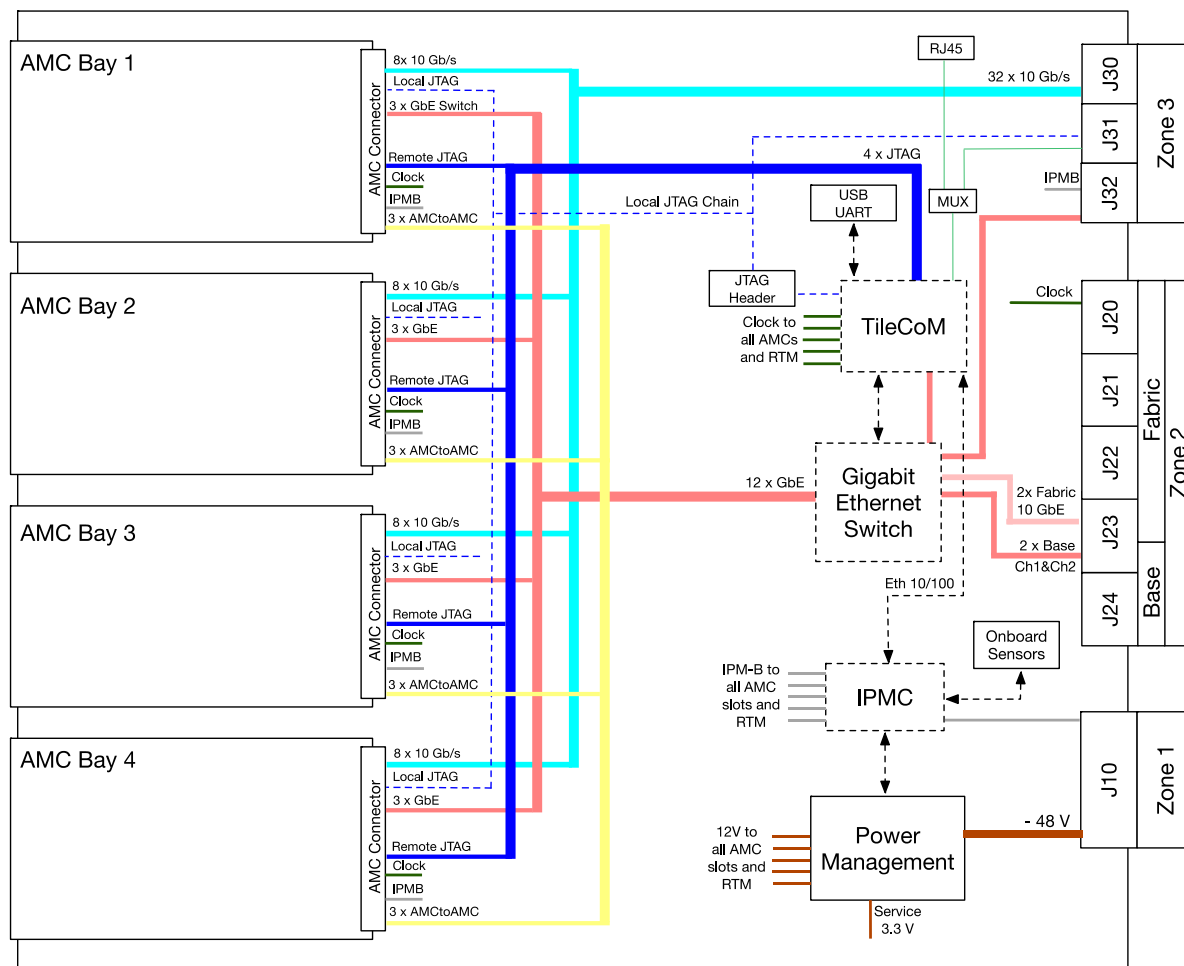
- **32 TilePPr boards in ATCA format:** ATCA carrier + 4 Compact Processing Modules
- **32 TileTDAQ-I:** Preprocesses trigger data and interfaces with L0Calo, L0Muon and FELIX system



ATCA Carrier Base Board



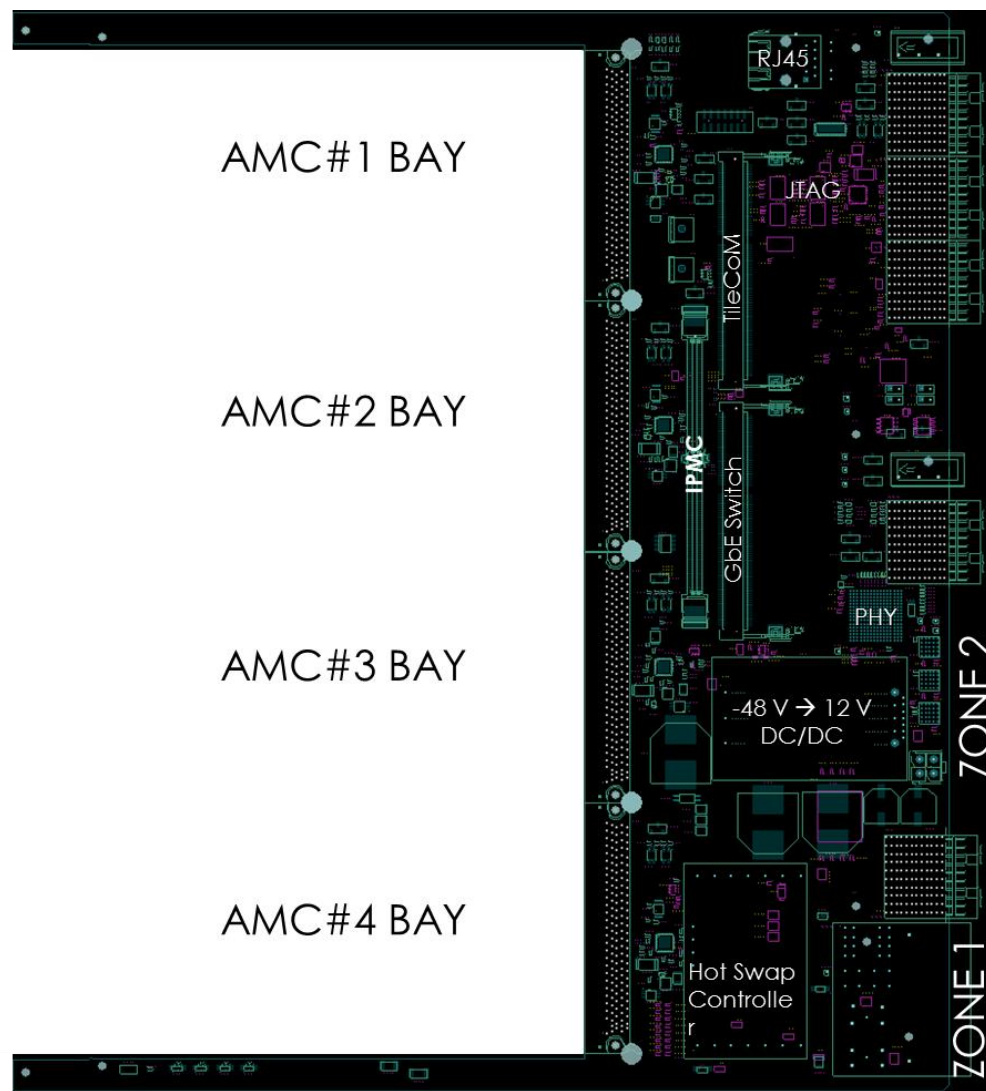
- Full-Size ATCA board
 - 14 layers, FR4 dielectric
 - 2.4 mm thickness
 - PCB cutaway to improve cooling
- Zone 1: Power distribution to CPMs and TDAQ-I
 - Max power of 400 W
- Zone 2: GbE + XAUI 10G
 - Communication with rest of the ecosystem
- Zone 3: Communication between CPMs and TDAQ-I
 - GbE lines, 16 Gbps lines
- First prototypes being produced



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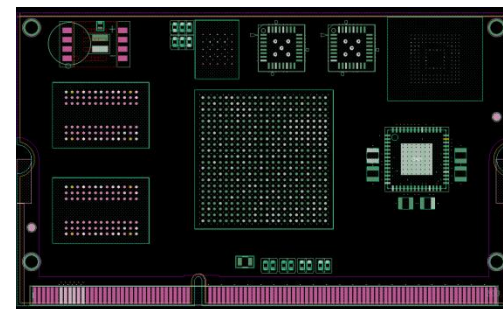




- Compact, replaceable and upgradeable solution

- TileCoM - Computer on Module

- Embedded Linux – PetaLinux distribution
- Remote programming, DCS monitoring, clock generation for standalone tests
- Xilinx Zynq UltraScale+ XCZU2CG + 512 MB DDR4
- 10 layers - DDR3 form factor (67.6 mm x **40.00 mm**)



Prelayout of the TileCoM

- Ethernet switch module

- Unmanaged Ethernet Switch chip Broadcom BCM5396
- 16 GbE connection between CPMs and TDAQ-I
- 6 layers - DDR3 form factor (67.6 mm x 30.00 mm)



GbE switch

- IPMC mezzanine board (CERN)

- Microsemi A2F200, DIMM-DDR3 VLP form factor
- Hot swap, sensor monitoring, power management

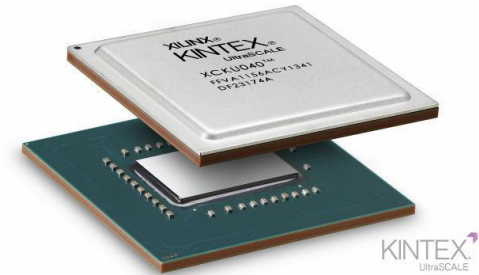


IPMC mezzanine board

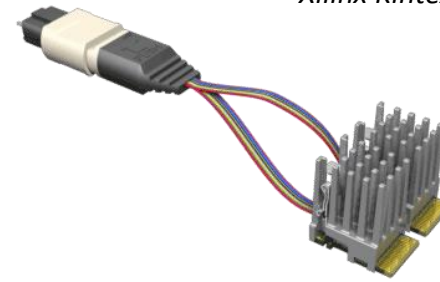
Compact Processing Module



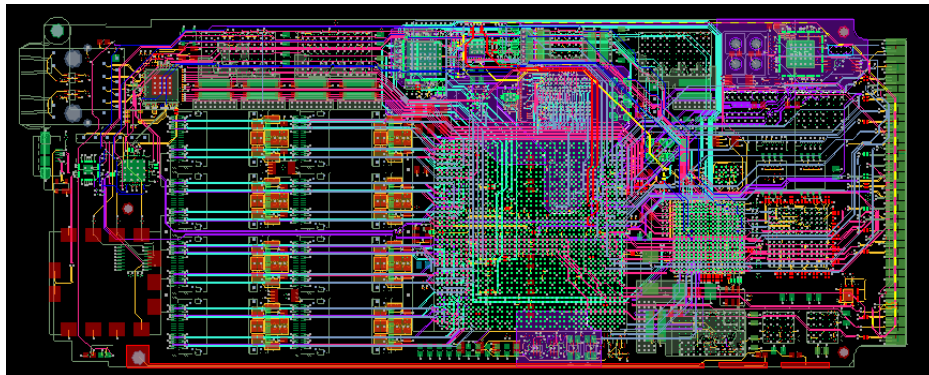
- Single AMC board with Kintex Ultrascale FPGA
 - 32 bidir-channels in 8 Samtec Firefly modules
 - 16 bidir-channels through backplane (PCIe, GbE)
 - Different line rates & clocking schemas supported
- High bandwidth readout system
 - Up to 500 Gbps via optics
 - Up to 260 Gbps via electrical backplane
- First prototypes at the end of March



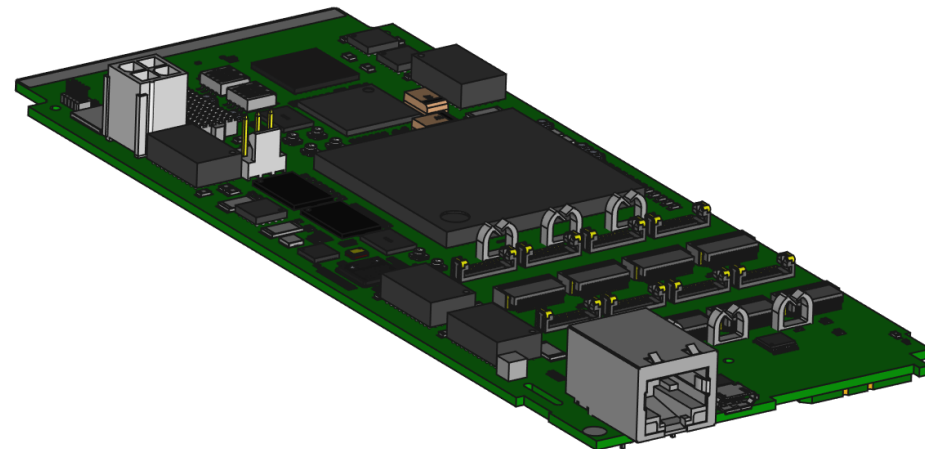
Xilinx Kintex UltraScale



Samtec FireFly module

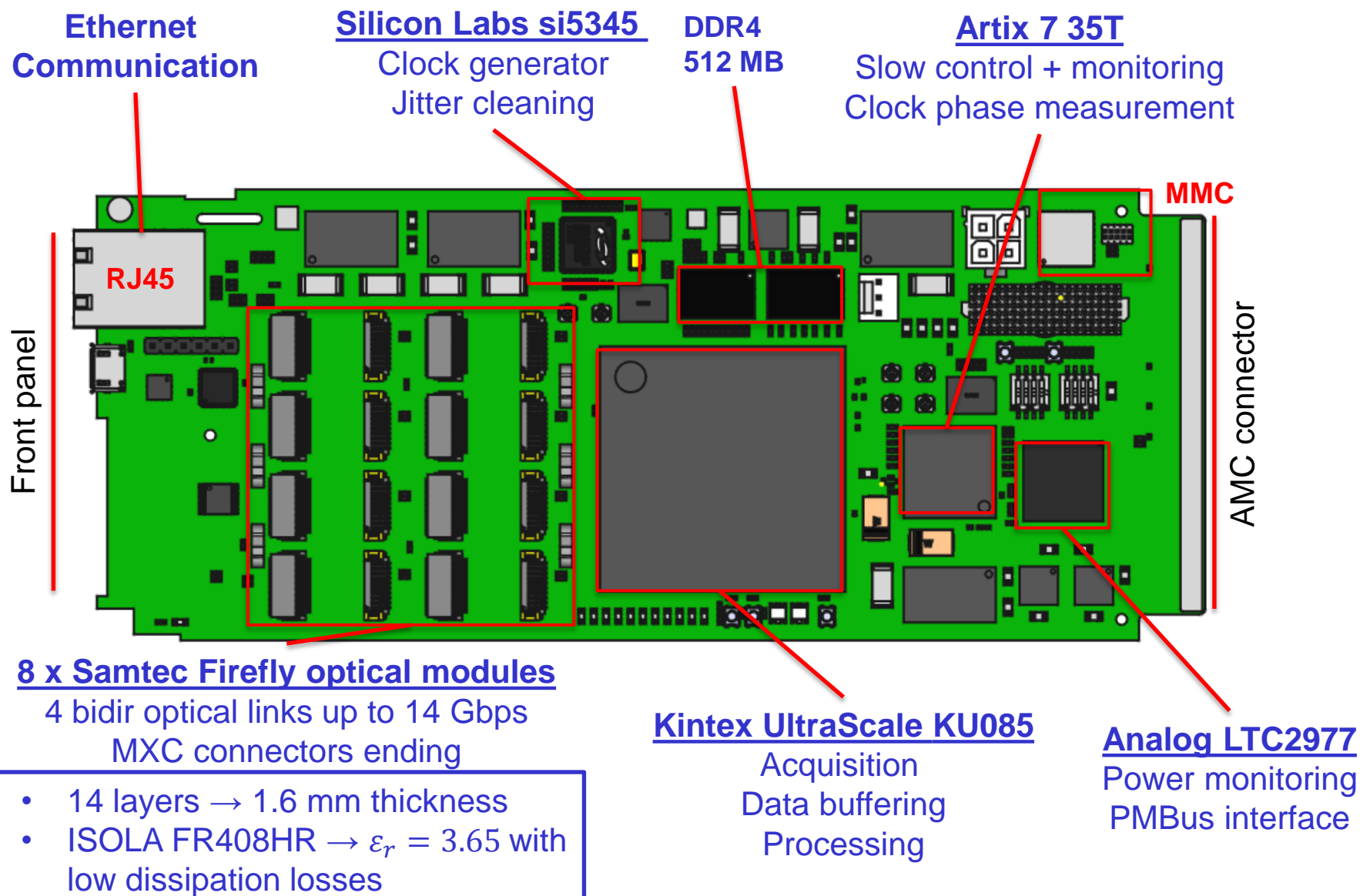


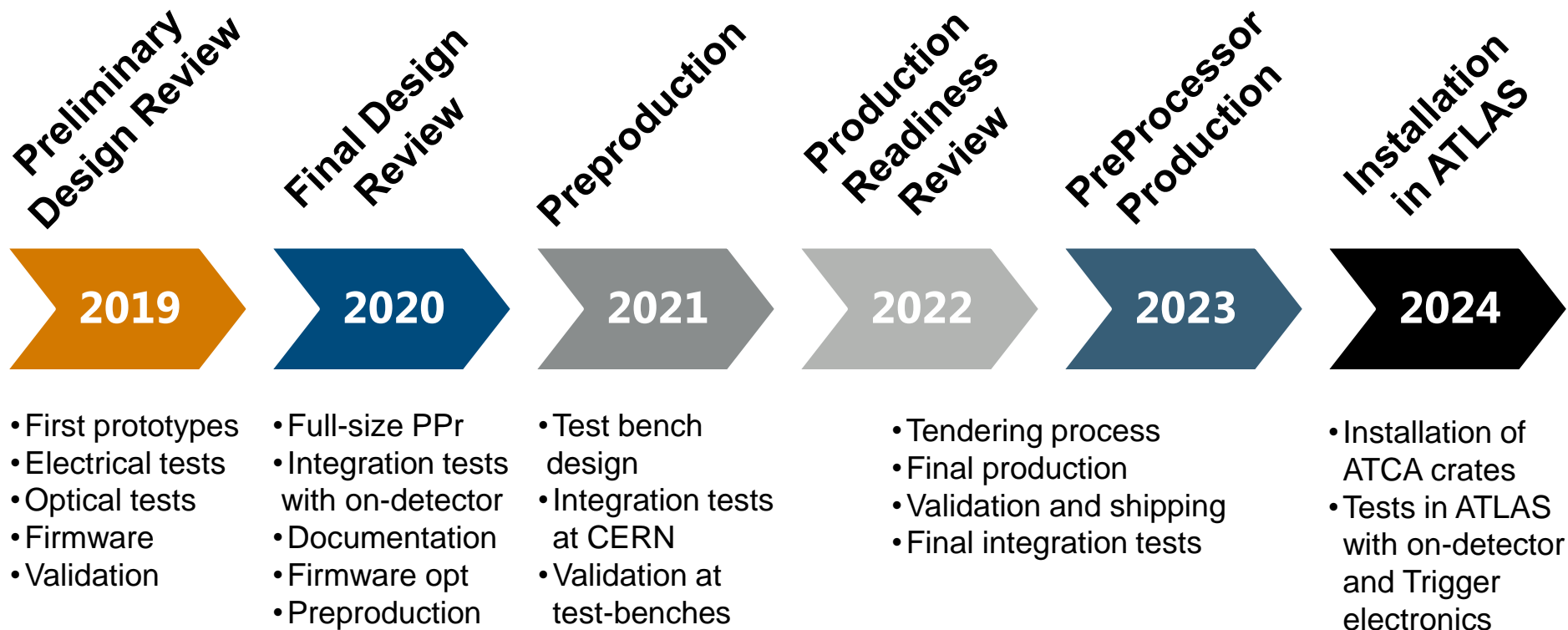
Layout of the Compact Processing Module



3D model of the Compact Processing Module

Compact Processing Module





- Preproduction (25%) from Q3 2020 to Q1 2022
 - 8 ATCA carriers, 32 CPMs
- Final production (75%) from Q2 2022 to Q3 2023
 - 24 ATCA carriers, 96 CPMs



- Complete redesign of the on-detector and off-detector readout electronics for the HL-LHC
- Development of readout electronics prototypes are done and tested
- Fully operational PreProcessor prototype has been designed and qualified
- Extensively tested in several test beam campaigns during 2015 and 2018
 - All prototypes showed a good performance
 - Readout electronics implements the clock and data architecture for HL-LHC
- Insertion of a demonstrator in ATLAS experiment during May 2019
- Full-size PreProcessor modules are under design / production
 - ATCA carrier + 4 Compact Processing Modules
 - First units expected for Q1 2019



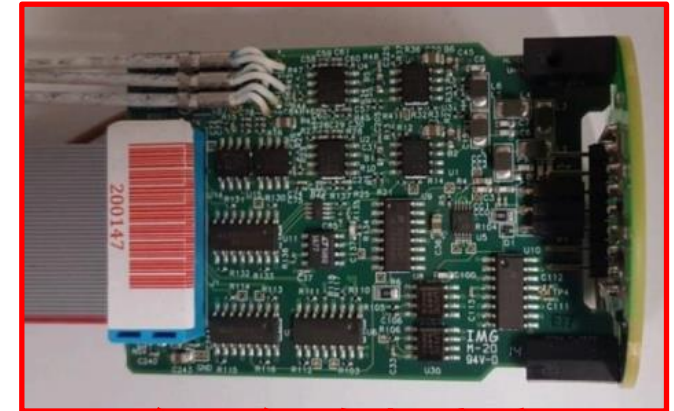


BACKUP



● Front-end boards: FENICS cards

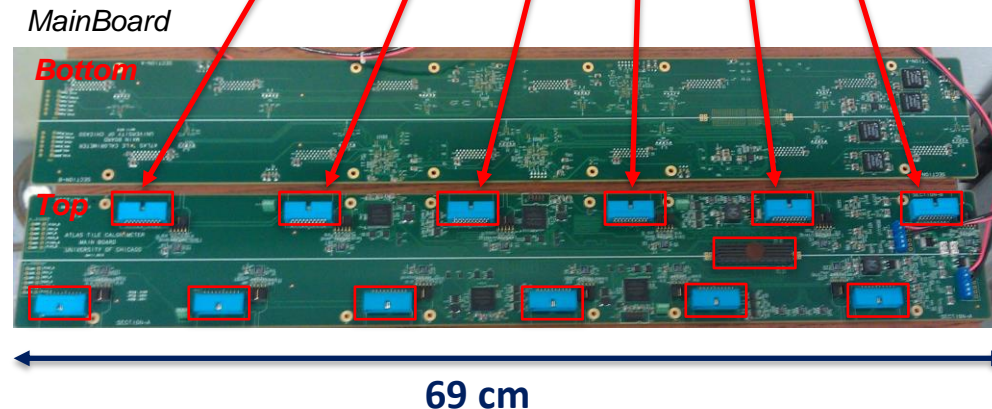
- **PMT pulse shaping**
- Shaper with bi-gain output: $1 \times \text{LG} + 1 \times \text{HG}$
- High precision slow integrator
- Design based on current 3in1 cards
 - Improved noise and linearity
 - Improved calibration circuitry



FENICS cards

● MainBoard

- **Digitize analog signals coming from 12 FEBs**
- Routes the digitized data from the ADCs to the DaughterBoards
- Digital control of the FEBs
- HG and LG, 12-bit samples @40 Msps
- TID, NIEL, SEE tests performed



DaughterBoard



- **High-speed link with the back-end electronics**

- Data collection and transmission
- Clock and command distribution
- Data link redundancy

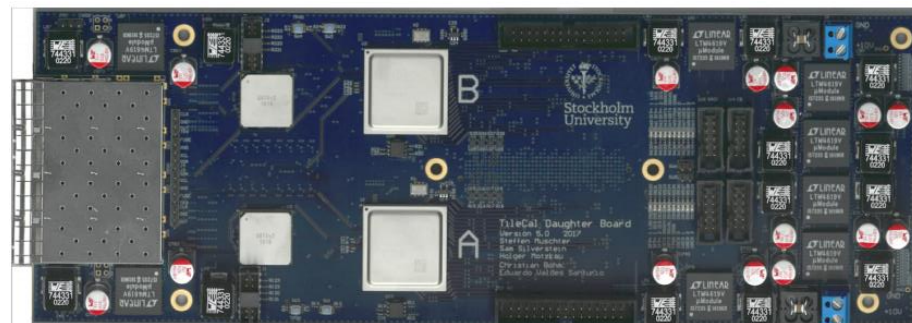
- Daughterboard version 5

- 2 × GigaBit Transceiver (GBT) chips
- 2 × Xilinx UltraScale+ FPGAs
- 4 × SFP modules → ~40 Gbps

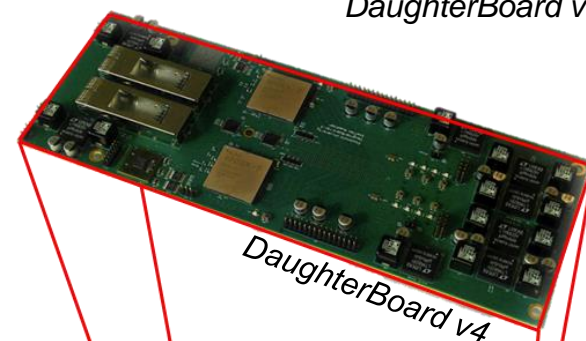
- TID tests with ~ 9 MeV electron beam

- SEE and SEL tests done with 58 MeV and 226 MeV proton beam

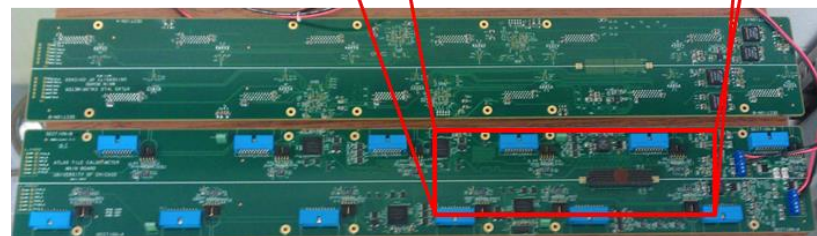
- Soft error rate is low → Triple redundancy
- No destructive effects observed



DaughterBoard v5

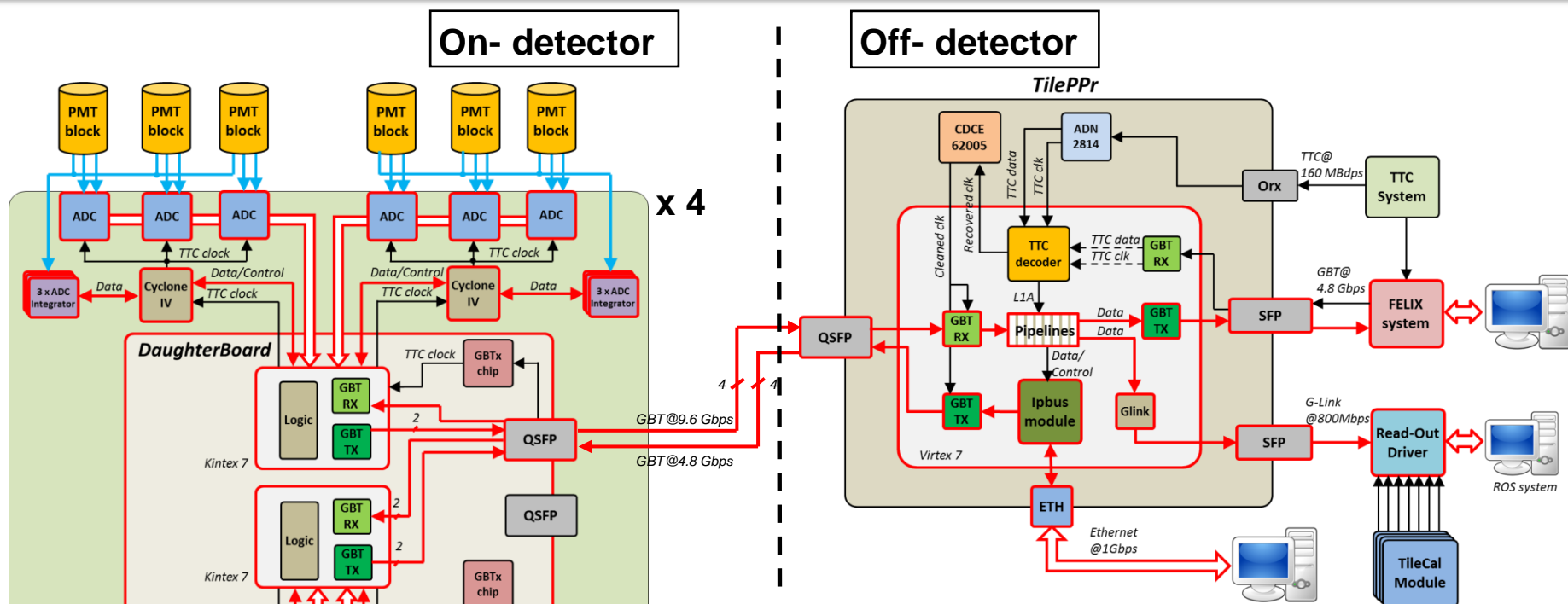


DaughterBoard v4



MainBoard

Clock and dataflow schema



- High-speed links with fixed and deterministic latency
 - 9.6/4.8 Gbps GigaBit Transceiver protocol
- Clock is transmitted embedded with commands
- On-detector sends digitized PMT signals at 40 MHz
- Two independent readout paths:
 - FELIX system / Legacy Read Out Drivers



- Detailed design of 10 Gbps lines
 - Differential and characteristic impedances
 - Supression of impedance discontinuities
 - Differential via design
 - DC-coupling capacitors
 - S-parameters extraction for crosstalk studies: FEXT and NEXT
 - Post-layout simulations to evaluate the total jitter
- Power distribution design
 - 10 voltage regulators: low noise design
 - Simulation of voltage drops due to high currents (IR drops)

